

Product/Process Change Notifications



PCN - 15 069

Release Date: July 14 2015

Product Name:	DDR4 PF			
	DDR4 PF			
Product Manager:	Bonnie Liu			
Subject:	Notification of Change with immediate effectivity			
Distribution:	General			
Type of Change:	Location Change			
Change Description:	1. Change manufacturing site from FCI Dongguan to FCI Senai. 2. Housing and latch resin changed from Halogen to Low Halogen type.			
Reason for Change:	<p>Change 1 : FCI Dongguan was developing the DDR4 PF in Y2013 to support customer in NPI stage. A soft tooling, developed to produce small Qty is now out of life and cannot support further orders.</p> <p>For better consolidation of plant resource and manufacturing capacity, we decided to develop hard tooling for DDR4 PF (terminal stamping die (2*4out), Housing Mold(4 Cavity) and manual assembly line in FCI Senai, Malaysia and FCI Jurong, Singapore.</p> <p>Below is the specific site of each process:</p> <ul style="list-style-type: none"> Terminal stamping & Plating will be at FCI Jurong, Singapore. Housing molding & Assembly line will be at FCI Senai, Malaysia. Latch Molding will be still at DG since common parts are shared between DDR4 SMT, TH and PF type. <p>Change 2: Change current resin with Halogen into Low Halogen for both Housing and latch.</p>			
Affected Parts:	Attached list.			
Effective Date of Change:	July 30, 2015			
Last Time Buy Date:	NA			
Last Disty Return Date:	NA			
Last Time Shipment Date	NA			
Datasheet Attached?	NA			
Qual/Test Data Attached?	NA			
Samples Availability Date:	July	30	2015	
Available Alternatives?	N/A			
Questions?	<i>Contact your local FCI Representative, or Product Manager</i>			
	<i>Bonnie Liu/ Product Manager</i>			
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Note:

Customer shall intimate the product Manager any Concern regarding the PCN within 3 weeks of the release date.
 PCN is considered approved by the customer if no communication is received within 3 weeks